



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Heinen

Art Unit: 2815

Serial No.: 09/186,973

Examiner: Cruz L.

Filed: 11/05/98

Docket: TI-23158

For: Wafer-Scale Assembly of Chip-Size Packages

AMENDMENT 37 CFR 1.115

December 11, 2000

Assistant Commissioner
for Patents
Washington, D.C. 20231

MAILING CERTIFICATE UNDER 37 C.F.R. 1.8(A)
I hereby certify that the above correspondence is being
deposited with the U.S. Postal Service as First Class Mail in
an envelope addressed to: Assistant Commissioner for
Patents, Washington, D.C. 20231 on December 11, 2000.

Nancy Thornton

Sir:

Responsive to the Office Action of August 28, 2000, please amend the
application as follows:

Page 12, line 6, delete "18of" and insert -- 18 of -- .

Please amend claim 1 as follows:

1. (Amended) A semiconductor assembly comprising:

a semiconductor wafer [having] comprising a plurality of undivided integrated circuits
joined together by semiconductor crystal, each circuit having a plurality of metal contact
pads as electrical entry and exit ports
an electrically conductive array, substantially parallel to [the surface of] said wafer,
comprising a multitude of coupling members positioned do that at least one of said
coupling members is electrically in contact with one circuit contact pad, respectively,
while remaining insulated from its adjacent member;